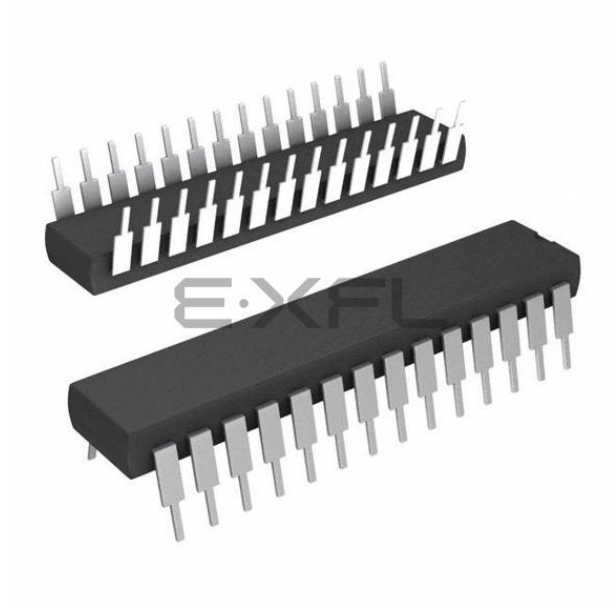

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f723-i-sp

1.0 DEVICE OVERVIEW

The PIC16(L)F722/3/4/6/7 devices are covered by this data sheet. They are available in 28/40/44-pin packages. Figure 1-1 shows a block diagram of the PIC16F722/723/726/PIC16LF722/723/726 devices and Figure 1-2 shows a block diagram of the PIC16F724/727/PIC16LF724/727 devices. Table 1-1 shows the pinout descriptions.

TABLE 1-1: PIC16(L)F722/3/4/6/7 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RB4/AN11/CPS4	RB4	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN11	AN	—	A/D Channel 11 input.
	CPS4	AN	—	Capacitive sensing input 4.
RB5/AN13/CPS5/T1G	RB5	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN13	AN	—	A/D Channel 13 input.
	CPS5	AN	—	Capacitive sensing input 5.
	T1G	ST	—	Timer1 Gate input.
RB6/ICSPCLK/ICDCLK	RB6	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	ICSPCLK	ST	—	Serial Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
RB7/ICSPDAT/ICDDAT	RB7	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ICDDAT	ST	—	In-Circuit Data I/O.
RC0/T1OSO/T1CKI	RC0	ST	CMOS	General purpose I/O.
	T1OSO	XTAL	XTAL	Timer1 oscillator connection.
	T1CKI	ST	—	Timer1 clock input.
RC1/T1OSI/CCP2	RC1	ST	CMOS	General purpose I/O.
	T1OSI	XTAL	XTAL	Timer1 oscillator connection.
	CCP2	ST	CMOS	Capture/Compare/PWM2.
RC2/CCP1	RC2	ST	CMOS	General purpose I/O.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
RC3/SCK/SCL	RC3	ST	CMOS	General purpose I/O.
	SCK	ST	CMOS	SPI clock.
	SCL	I^2C	OD	I^2C clock.
RC4/SDI/SDA	RC4	ST	CMOS	General purpose I/O.
	SDI	ST	—	SPI data input.
	SDA	I^2C	OD	I^2C data input/output.
RC5/SDO	RC5	ST	CMOS	General purpose I/O.
	SDO	—	CMOS	SPI data output.
RC6/TX/CK	RC6	ST	CMOS	General purpose I/O.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
RC7/RX/DT	RC7	ST	CMOS	General purpose I/O.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
RD0/CPS8	RD0	ST	CMOS	General purpose I/O.
	CPS8	AN	—	Capacitive sensing input 8.
RD1/CPS9	RD1	ST	CMOS	General purpose I/O.
	CPS9	AN	—	Capacitive sensing input 9.
RD2/CPS10	RD2	ST	CMOS	General purpose I/O.
	CPS10	AN	—	Capacitive sensing input 10.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C = Schmitt Trigger input with I^2C
HV = High Voltage XTAL = Crystal levels

TABLE 3-4: INITIALIZATION CONDITION FOR REGISTERS

Register	Address	Power-on Reset/ Brown-out Reset(1)	$\overline{\text{MCLR}}$ Reset/ WDT Reset	Wake-up from Sleep through Interrupt/Time out
W	—	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h/80h/ 100h/180h	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR0	01h/101h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h/82h/ 102h/182h	0000 0000	0000 0000	PC + 1(3)
STATUS	03h/83h/ 103h/183h	0001 1xxx	000q quuu(4)	uuuq quuu(4)
FSR	04h/84h/ 104h/184h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	05h	xxxx xxxx	xxxx xxxx	uuuu uuuu
PORTB	06h	xxxx xxxx	xxxx xxxx	uuuu uuuu
PORTC	07h	xxxx xxxx	xxxx xxxx	uuuu uuuu
PORTD(6)	08h	xxxx xxxx	xxxx xxxx	uuuu uuuu
PORTE	09h	---- xxxx	---- xxxx	---- uuuu
PCLATH	0Ah/8Ah/ 10Ah/18Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh/8Bh/ 10Bh/18Bh	0000 000x	0000 000x	uuuu uuuu(2)
PIR1	0Ch	0000 0000	0000 0000	uuuu uuuu(2)
PIR2	0Dh	---- ---0	---- ---0	---- ---u
TMR1L	0Eh	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	0Fh	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	10h	0000 00-0	uuuu uu-u	uuuu uu-u
TMR2	11h	0000 0000	0000 0000	uuuu uuuu
T2CON	12h	-000 0000	-000 0000	-uuu uuuu
SSPBUF	13h	xxxx xxxx	xxxx xxxx	uuuu uuuu
SSPCON	14h	0000 0000	0000 0000	uuuu uuuu
CCPR1L	15h	xxxx xxxx	xxxx xxxx	uuuu uuuu
CCPR1H	16h	xxxx xxxx	xxxx xxxx	uuuu uuuu
CCP1CON	17h	--00 0000	--00 0000	--uu uuuu
RCSTA	18h	0000 000x	0000 000x	uuuu uuuu
TXREG	19h	0000 0000	0000 0000	uuuu uuuu
RCREG	1Ah	0000 0000	0000 0000	uuuu uuuu
CCPR2L	1Bh	xxxx xxxx	xxxx xxxx	uuuu uuuu
CCPR2H	1Ch	xxxx xxxx	xxxx xxxx	uuuu uuuu
CCP2CON	1Dh	--00 0000	--00 0000	--uu uuuu
ADRES	1Eh	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	1Fh	--00 0000	--00 0000	--uu uuuu
OPTION_REG	81h/181h	1111 1111	1111 1111	uuuu uuuu
TRISA	85h	1111 1111	1111 1111	uuuu uuuu
TRISB	86h	1111 1111	1111 1111	uuuu uuuu
TRISC	87h	1111 1111	1111 1111	uuuu uuuu
TRISD(6)	88h	1111 1111	1111 1111	uuuu uuuu
TRISE	89h	---- 1111	---- 1111	---- uuuu
PIE1	8Ch	0000 0000	0000 0000	uuuu uuuu
PIE2	8Dh	---- ---0	---- ---0	---- ---u

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.

Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON and/or PIR1 and PIR2 will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 3-5 for Reset value for specific condition.

5: If Reset was due to brown-out, then bit 0 = 0. All other Resets will cause bit 0 = u.

6: PIC16F724/727/PIC16LF724/727 only.

4.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to the **Section 19.0 "Power-Down Mode (Sleep)"** for more details.

4.4 INT Pin

The external interrupt, INT pin, causes an asynchronous, edge-triggered interrupt. The INTEDG bit of the OPTION register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector. This interrupt is disabled by clearing the INTE bit of the INTCON register.

4.5 Context Saving

When an interrupt occurs, only the return PC value is saved to the stack. If the ISR modifies or uses an instruction that modifies key registers, their values must be saved at the beginning of the ISR and restored when the ISR completes. This prevents instructions following the ISR from using invalid data. Examples of key registers include the W, STATUS, FSR and PCLATH registers.

Note:	The microcontroller does not normally require saving the PCLATH register. However, if computed GOTO's are used, the PCLATH register must be saved at the beginning of the ISR and restored when the ISR is complete to ensure correct program flow.

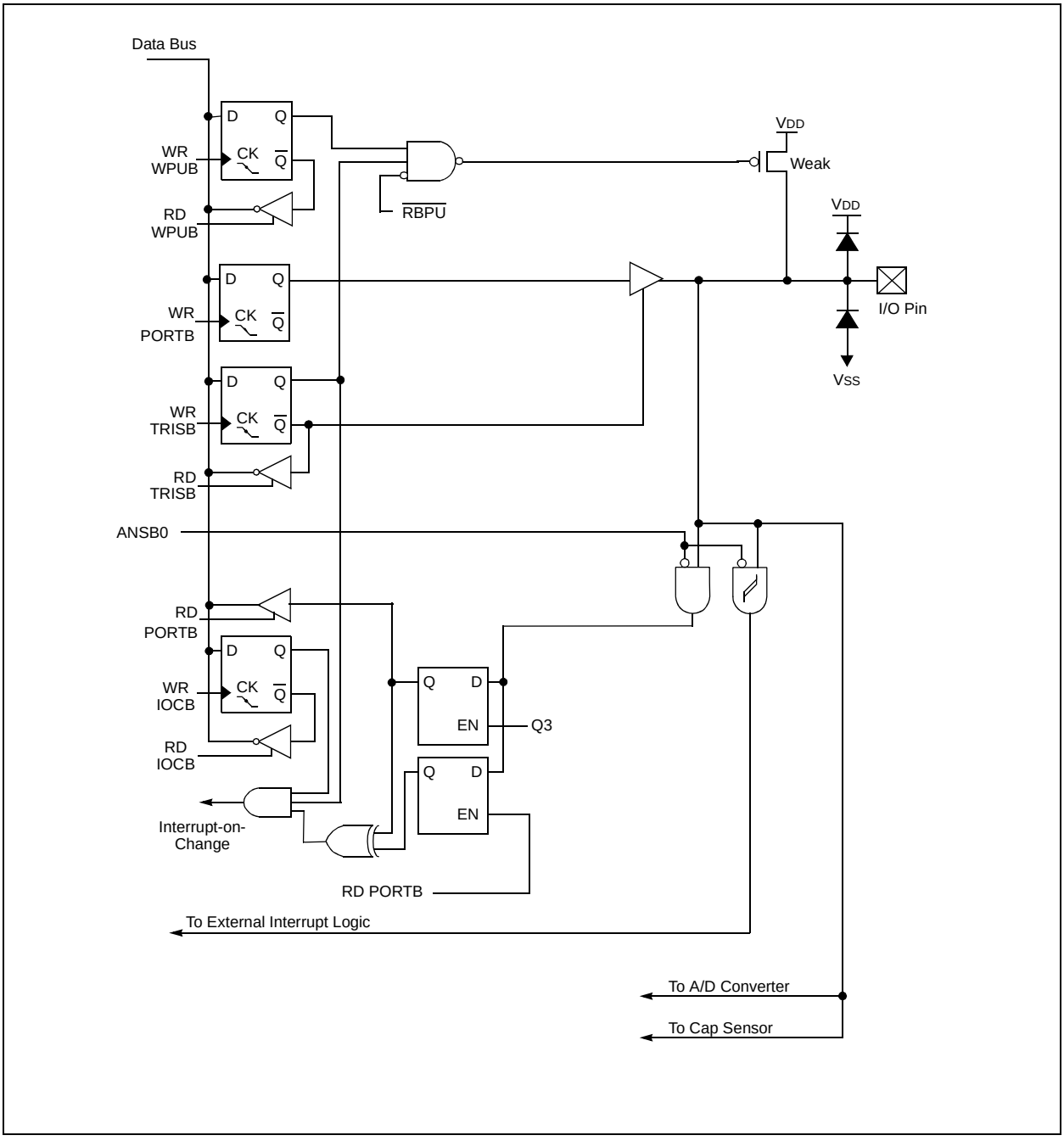
The code shown in Example 4-1 can be used to do the following.

- Save the W register
- Save the STATUS register
- Save the PCLATH register
- Execute the ISR program
- Restore the PCLATH register
- Restore the STATUS register
- Restore the W register

Since most instructions modify the W register, it must be saved immediately upon entering the ISR. The SWAPF instruction is used when saving and restoring the W and STATUS registers because it will not affect any bits in the STATUS register. It is useful to place W_TEMP in shared memory because the ISR cannot predict which bank will be selected when the interrupt occurs.

The processor will branch to the interrupt vector by loading the PC with 0004h. The PCLATH register will remain unchanged. This requires the ISR to ensure that the PCLATH register is set properly before using an instruction that causes PCLATH to be loaded into the PC. See **Section 2.3 "PCL and PCLATH"** for details on PC operation.

FIGURE 6-7: BLOCK DIAGRAM OF RB0



6.5 PORTD and TRISD Registers

PORTD is a 8-bit wide, bidirectional port. The corresponding data direction register is TRISD (Register 6-13). Setting a TRISD bit (= 1) will make the corresponding PORTD pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISD bit (= 0) will make the corresponding PORTD pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 6-4 shows how to initialize PORTD.

Reading the PORTD register (Register 6-12) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch.

Note:	PORTD is available on PIC16F724/LF724 and PIC16F727/LF727 only.

The TRISD register (Register 6-13) controls the PORTD pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISD register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

EXAMPLE 6-4: INITIALIZING PORTD

```
BANKSEL PORTD        ;
CLRF    PORTD        ;Init PORTD
BANKSEL ANSELD
CLRF    ANSELD       ;Make PORTD digital
BANKSEL TRISD        ;
MOVLW   B'00001100'  ;Set RD<3:2> as inputs
MOVWF   TRISD        ;and set RD<7:4,1:0>
                     ;as outputs
```

6.5.1 ANSELD REGISTER

The ANSELD register (Register 6-9) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELD bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELD bits has no affect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

Note:	The ANSELD register must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'.

REGISTER 6-12: PORTD: PORTD REGISTER(1)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **RD<7:0>**: PORTD General Purpose I/O Pin bits
1 = Port pin is > V_{IH}
0 = Port pin is < V_{IL}

Note 1: PORTD is not implemented on PIC16F722/723/726/PIC16LF722/723/726 devices, read as '0'.

7.5 Oscillator Tuning

The INTOSC is factory calibrated but can be adjusted in software by writing to the OSCTUNE register (Register 7-2).

The default value of the OSCTUNE register is '0'. The value is a 6-bit two's complement number.

When the OSCTUNE register is modified, the INTOSC frequency will begin shifting to the new frequency. Code execution continues during this shift. There is no indication that the shift has occurred.

REGISTER 7-2: OSCTUNE: OSCILLATOR TUNING REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

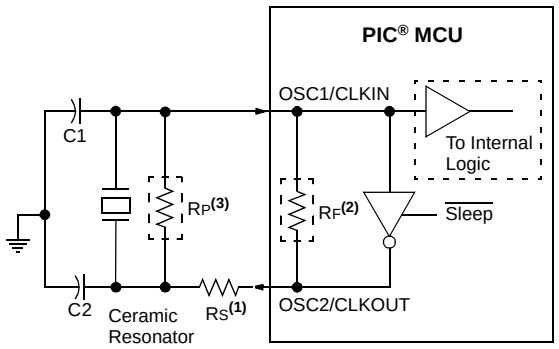
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** Frequency Tuning bits

01 1111 = Maximum frequency
01 1110 =
•
•
•
00 0001 =
00 0000 = Oscillator module is running at the factory-calibrated frequency.
11 1111 =
•
•
•
10 0000 = Minimum frequency

FIGURE 7-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (RS) may be required for ceramic resonators with low drive level.

2: The value of RF varies with the Oscillator mode selected.

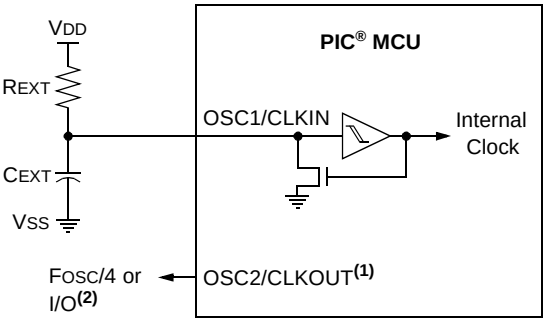
3: An additional parallel feedback resistor (RP) may be required for proper ceramic resonator operation.

7.6.4 EXTERNAL RC MODES

The external Resistor-Capacitor (RC) modes support the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required. There are two modes: RC and RCIO.

In RC mode, the RC circuit connects to OSC1. OSC2/CLKOUT outputs the RC oscillator frequency divided by 4. This signal may be used to provide a clock for external circuitry, synchronization, calibration, test or other application requirements. Figure 7-5 shows the external RC mode connections.

FIGURE 7-5: EXTERNAL RC MODES



Recommended values: 10 kΩ ≤ REXT ≤ 100 kΩ, <3V
3 kΩ ≤ REXT ≤ 100 kΩ, 3-5V
CEXT > 20 pF, 2-5V

Note 1: Alternate pin functions are described in **Section 6.1 "Alternate Pin Function"**.

2: Output depends upon RC or RCIO clock mode.

In RCIO mode, the RC circuit is connected to OSC1. OSC2 becomes an additional general purpose I/O pin.

The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- packaging variations in capacitance

The user also needs to take into account variation due to tolerance of external RC components used.

TABLE 7-1: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets(1)
CONFIG1(1)	—	$\overline{CP}$	MCLRE	$\overline{PWRTE}$	WDTE	FOSC2	FOSC1	FOSC0	—	—
OSCCON	—	—	IRCF1	IRCF0	ICSL	ICSS	—	—	--10 qq--	--10 qq--
OSCTUNE	—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0	--00 0000	--uu uuuu

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by clock sources.

Note 1: See Configuration Word 1 (Register 8-1) for operation of all bits.

TABLE 9-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})				
ADC Clock Source	**ADCS<2:0>**	**20 MHz**	**16 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
Fosc/2	000	100 ns(2)	125 ns(2)	250 ns(2)	500 ns(2)	2.0 μs
Fosc/4	100	200 ns(2)	250 ns(2)	500 ns(2)	1.0 μs	4.0 μs
Fosc/8	001	400 ns(2)	0.5 μs(2)	1.0 μs	2.0 μs	8.0 μs(3)
Fosc/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs(3)
Fosc/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs(3)	32.0 μs(3)
Fosc/64	110	3.2 μs	4.0 μs	8.0 μs(3)	16.0 μs(3)	64.0 μs(3)
FRC	x11	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)

Legend: Shaded cells are outside of recommended range.

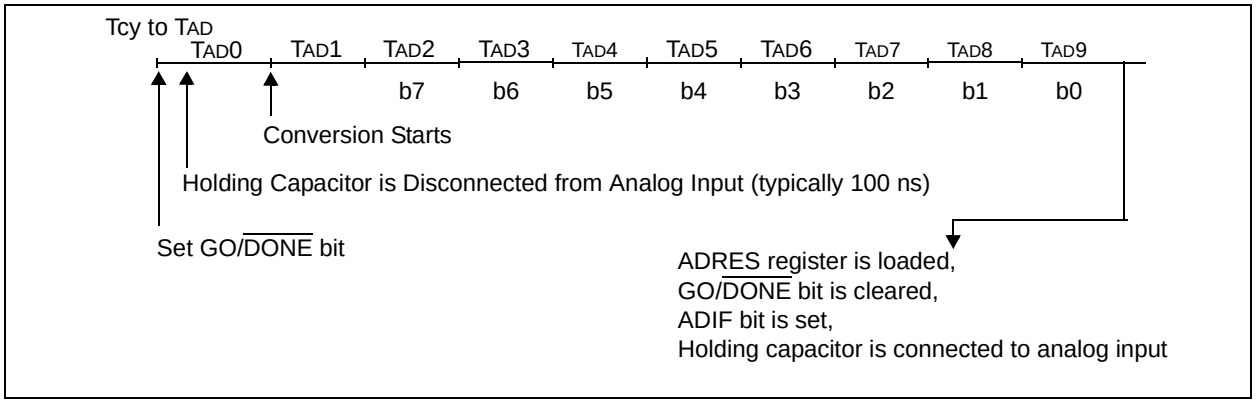
Note 1: The FRC source has a typical T_{AD} time of 1.6 μs for V_{DD}.

2: These values violate the minimum required T_{AD} time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the FRC clock source is only recommended if the conversion will be performed during Sleep.

FIGURE 9-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



9.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 9-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 9-3. **The maximum recommended impedance for analog sources is 10 kΩ**. As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 9-1 may be used. This equation assumes that 1/2 LSb error is used (256 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 9-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $5.0V$ V_{DD}

$$\begin{aligned} T_{ACQ} &= \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient} \\ &= T_{AMP} + T_C + T_{COFF} \\ &= 2\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)] \end{aligned}$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD} \text{ charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD} \text{ charge response to } V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: *Where n = number of bits of the ADC.*

Solving for T_C*:*

$$\begin{aligned} T_C &= -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/511) \\ &= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.001957) \\ &= 1.12\mu s \end{aligned}$$

Therefore:

$$\begin{aligned} T_{ACQ} &= 2MS + 1.12MS + [(50°C - 25°C)(0.05MS/°C)] \\ &= 4.42MS \end{aligned}$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

REGISTER 13-1: T2CON: TIMER2 CONTROL REGISTER

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **TOUTPS<3:0>:** Timer2 Output Postscaler Select bits

0000 = 1:1 Postscaler
0001 = 1:2 Postscaler
0010 = 1:3 Postscaler
0011 = 1:4 Postscaler
0100 = 1:5 Postscaler
0101 = 1:6 Postscaler
0110 = 1:7 Postscaler
0111 = 1:8 Postscaler
1000 = 1:9 Postscaler
1001 = 1:10 Postscaler
1010 = 1:11 Postscaler
1011 = 1:12 Postscaler
1100 = 1:13 Postscaler
1101 = 1:14 Postscaler
1110 = 1:15 Postscaler
1111 = 1:16 Postscaler

bit 2 **TMR2ON:** Timer2 On bit

1 = Timer2 is on
0 = Timer2 is off

bit 1-0 **T2CKPS<1:0>:** Timer2 Clock Prescale Select bits

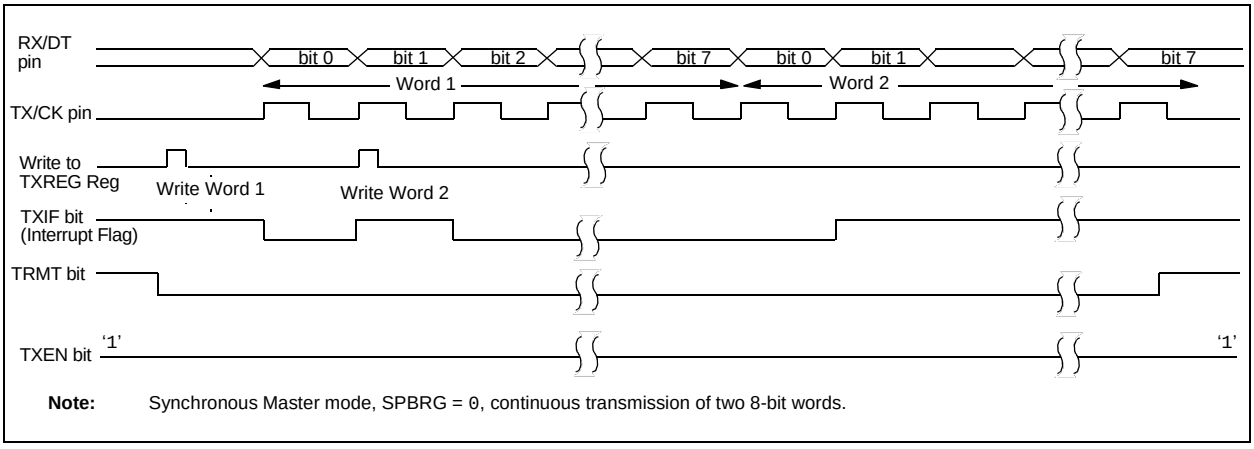
00 = Prescaler is 1
01 = Prescaler is 4
1x = Prescaler is 16

TABLE 13-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER2

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PR2	Timer2 Module Period Register								1111 1111	1111 1111
TMR2	Holding Register for the 8-bit TMR2 Register								0000 0000	0000 0000
T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for Timer2 module.

FIGURE 16-6: SYNCHRONOUS TRANSMISSION



Note: Synchronous Master mode, SPBRG = 0, continuous transmission of two 8-bit words.

FIGURE 16-7: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)

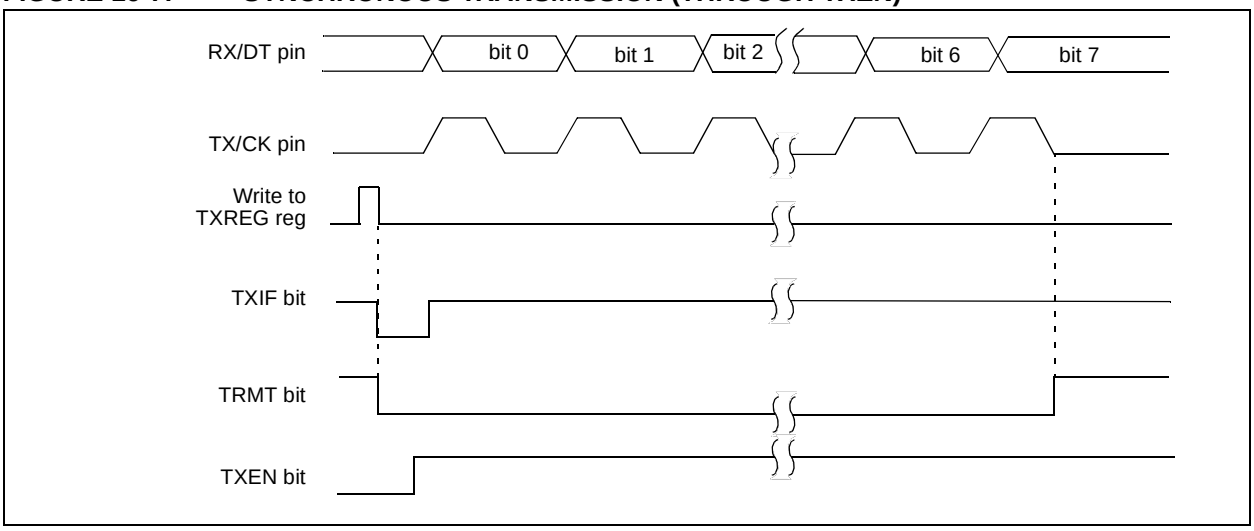
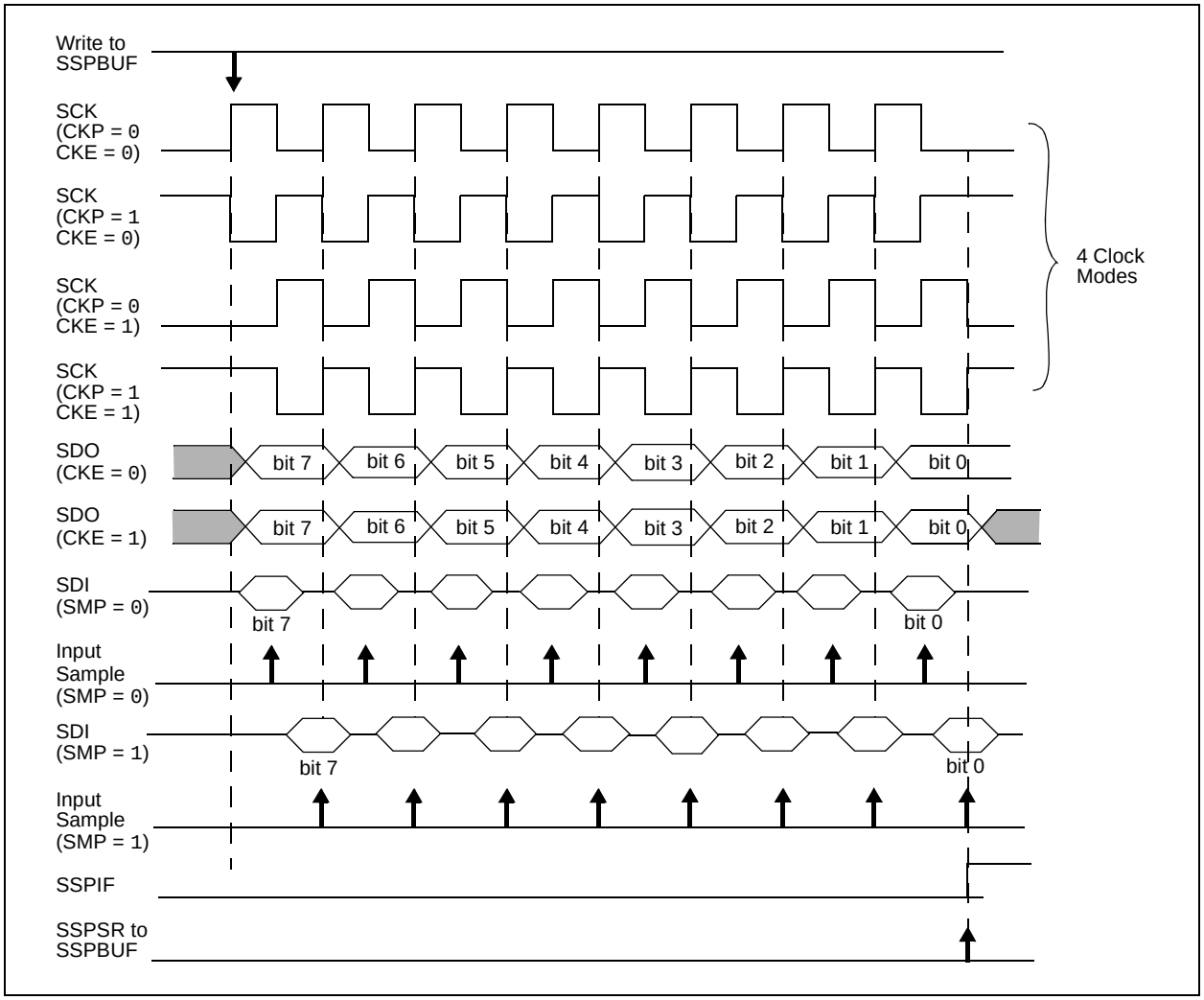


TABLE 16-6: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXREG	AUSART Transmit Data Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Synchronous Master Transmission.

FIGURE 17-3: SPI MASTER MODE WAVEFORM



EXAMPLE 17-1: LOADING THE SSPBUF (SSPSR) REGISTER

```
        BANKSEL   SSPSTAT      ;
LOOP    BTFSS     SSPSTAT, BF  ;Has data been received(transmit complete)?
        GOTO      LOOP         ;No
        BANKSEL   SSPBUF       ;
        MOVF      SSPBUF, W    ;WREG reg = contents of SSPBUF
        MOVWF     RXDATA       ;Save in user RAM, if data is meaningful
        MOVF      TXDATA, W    ;W reg = contents of TXDATA
        MOVWF     SSPBUF       ;New data to xmit
```

17.1.2.4 Slave Select Operation

The $\overline{SS}$ pin allows Synchronous Slave mode operation. The SPI must be in Slave mode with $\overline{SS}$ pin control enabled (SSPM<3:0> = 0100). The associated TRIS bit for the $\overline{SS}$ pin must be set, making $\overline{SS}$ an input.

In Slave Select mode, when:

- $\overline{SS}$ = 0, The device operates as specified in **Section 17.1.2 "Slave Mode"**.
- $\overline{SS}$ = 1, The SPI module is held in Reset and the SDO pin will be tri-stated.

Note 1:	When the SPI is in Slave mode with $\overline{SS}$ pin control enabled (SSPM<3:0> = 0100), the SPI module will reset if the $\overline{SS}$ pin is driven high.
2:	If the SPI is used in Slave mode with CKE set, the $\overline{SS}$ pin control must be enabled.

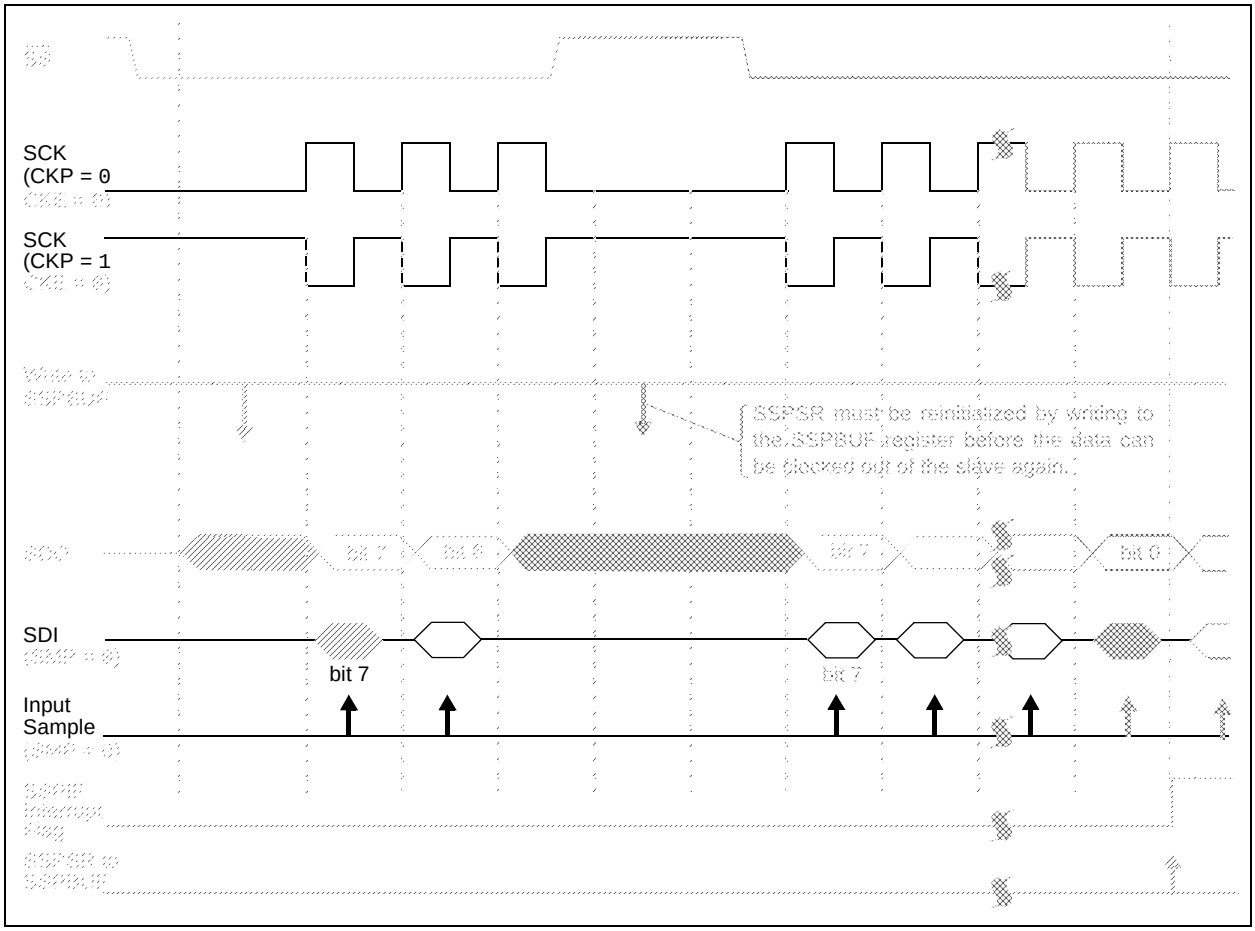
When the SPI module resets, the bit counter is cleared to '0'. This can be done by either forcing the $\overline{SS}$ pin to a high level or clearing the SSPEN bit. Figure 17-6 shows the timing waveform for such a synchronization event.

Note:	SSPSR must be reinitialized by writing to the SSPBUF register before the data can be clocked out of the slave again.

17.1.2.5 Sleep in Slave Mode

While in Sleep mode, the slave can transmit/receive data. The SPI Transmit/Receive Shift register operates asynchronously to the device on the externally supplied clock source. This allows the device to be placed in Sleep mode and data to be shifted into the SPI Transmit/Receive Shift register. When all eight bits have been received, the SSP Interrupt Flag bit will be set and if enabled, will wake the device from Sleep.

FIGURE 17-6: SLAVE SELECT SYNCHRONIZATION WAVEFORM

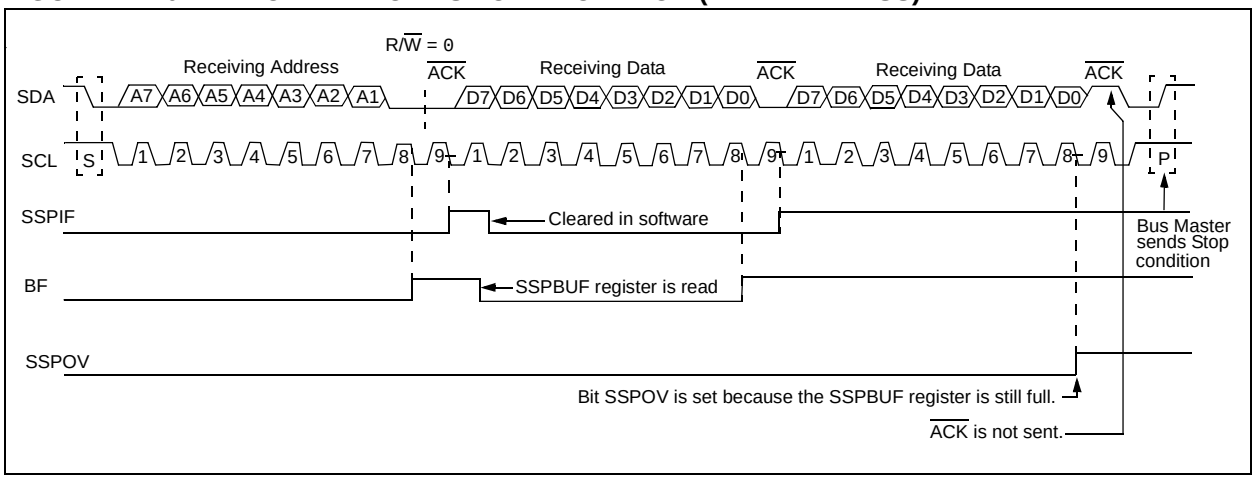


17.2.5 RECEPTION

When the R/$\overline{W}$ bit of the received address byte is clear, the master will write data to the slave. If an address match occurs, the received address is loaded into the SSPBUF register. An address byte overflow will occur if that loaded address is not read from the SSPBUF before the next complete byte is received.

An SSP interrupt is generated for each data transfer byte. The BF, R/$\overline{W}$ and D/$\overline{A}$ bits of the SSPSTAT register are used to determine the status of the last received byte.

FIGURE 17-10: I²C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)



22.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

22.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

22.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

22.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

22.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

TABLE 23-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±2%	—	16.0	—	MHz	0°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			±5%	—	16.0	—	MHz	-40°C ≤ TA ≤ +125°C
OS08A	MFOSC	Internal Calibrated MFINTOSC Frequency(2)	±2%	—	500	—	kHz	0°C ≤ TA ≤ +85°C VDD ≥ 2.5V
			±5%	—	500	10	kHz	-40°C ≤ TA ≤ +125°C
OS10*	TIOSC ST	HFINTOSC Wake-up from Sleep Start-up Time	—	—	5	8	µs	
		MFINTOSC Wake-up from Sleep Start-up Time	—	—	20	30	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

3: By design.

FIGURE 23-7: CLKOUT AND I/O TIMING

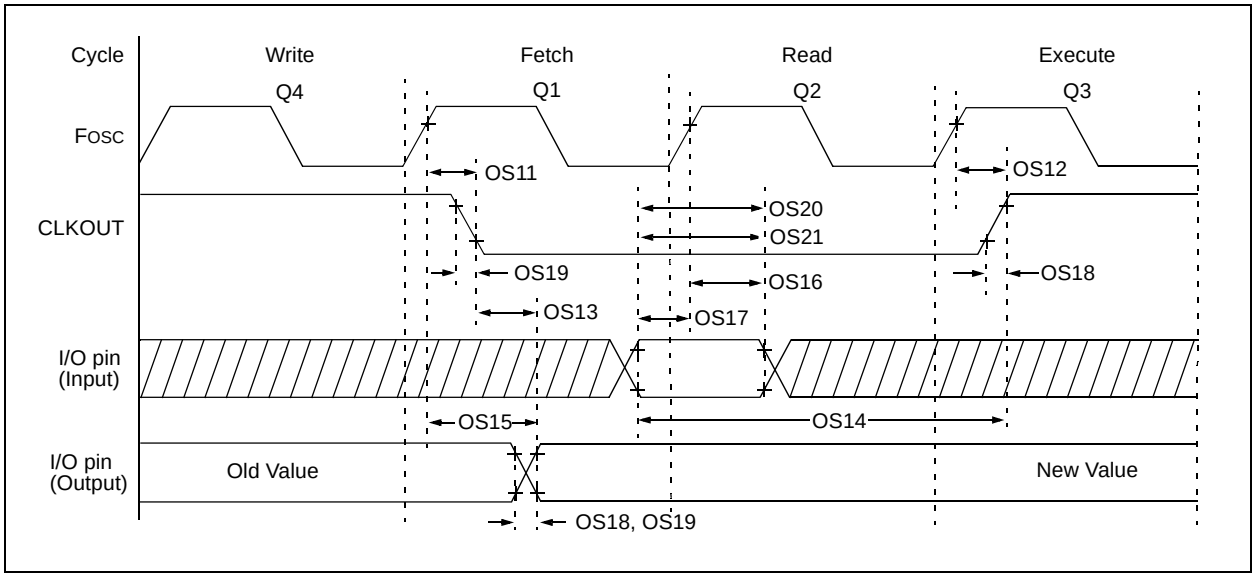


FIGURE 24-49: TTL INPUT THRESHOLD VIN vs. VDD OVER TEMPERATURE

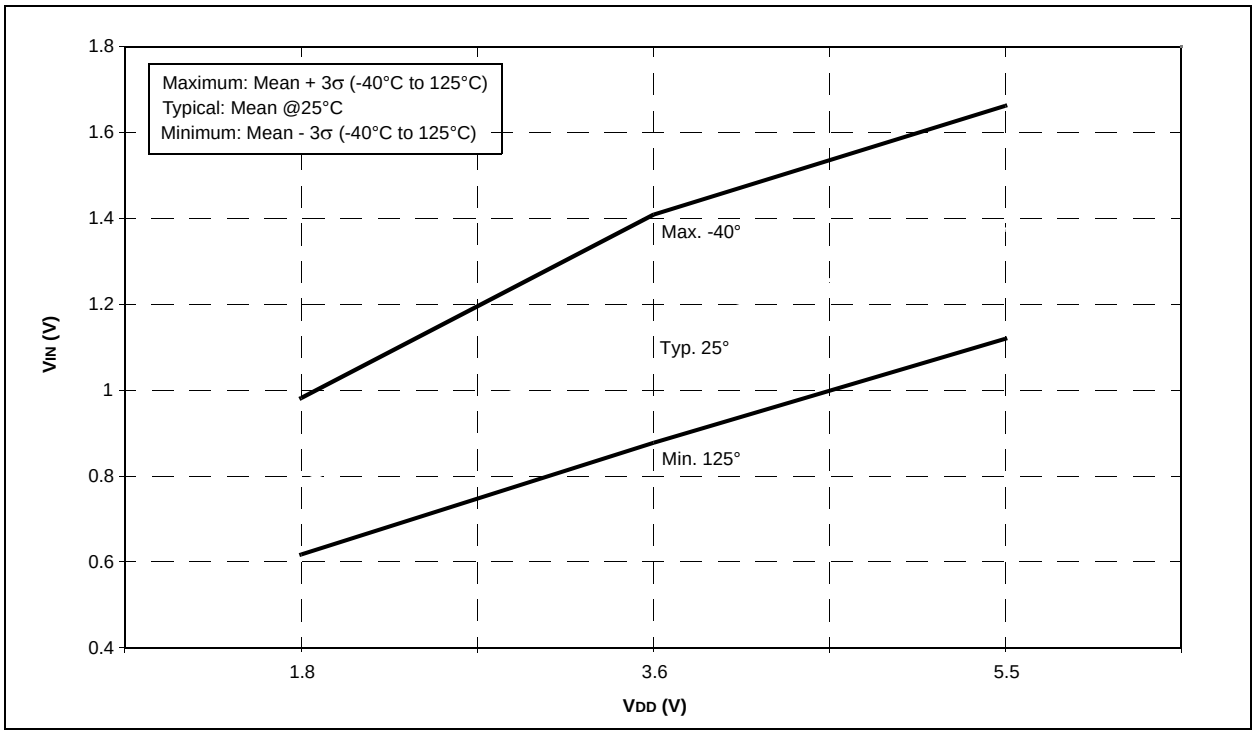
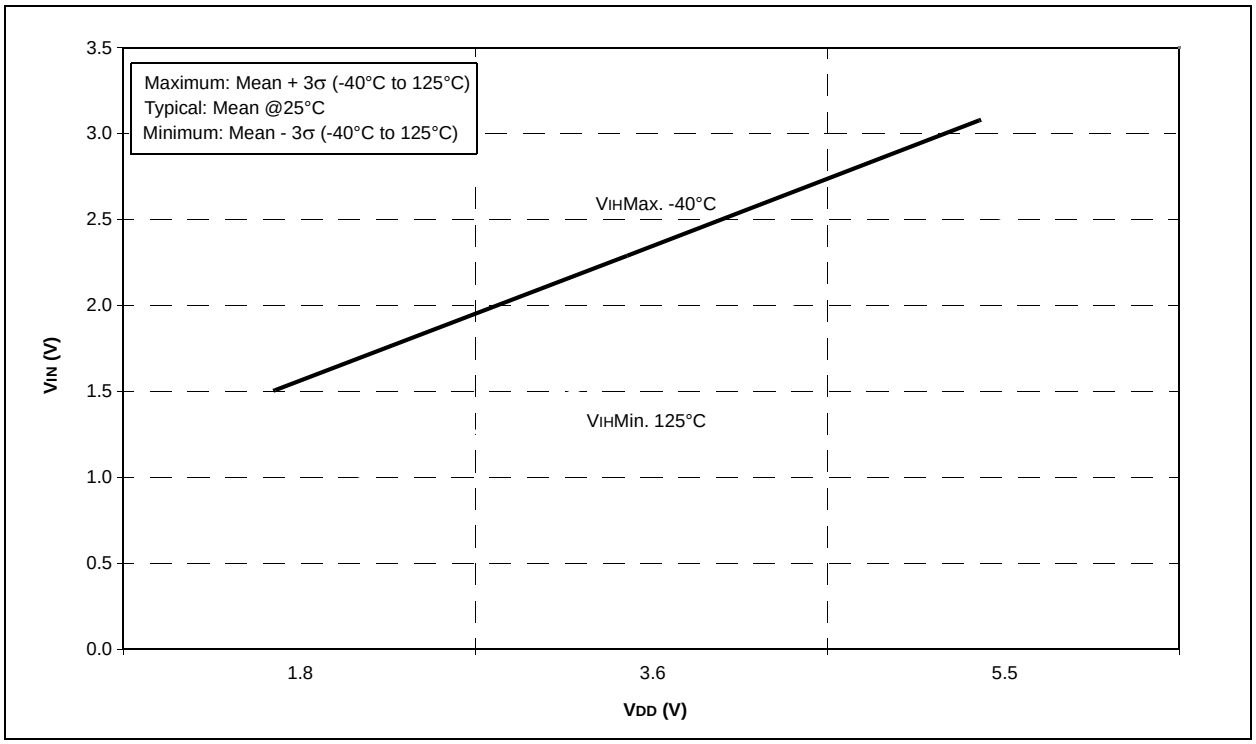
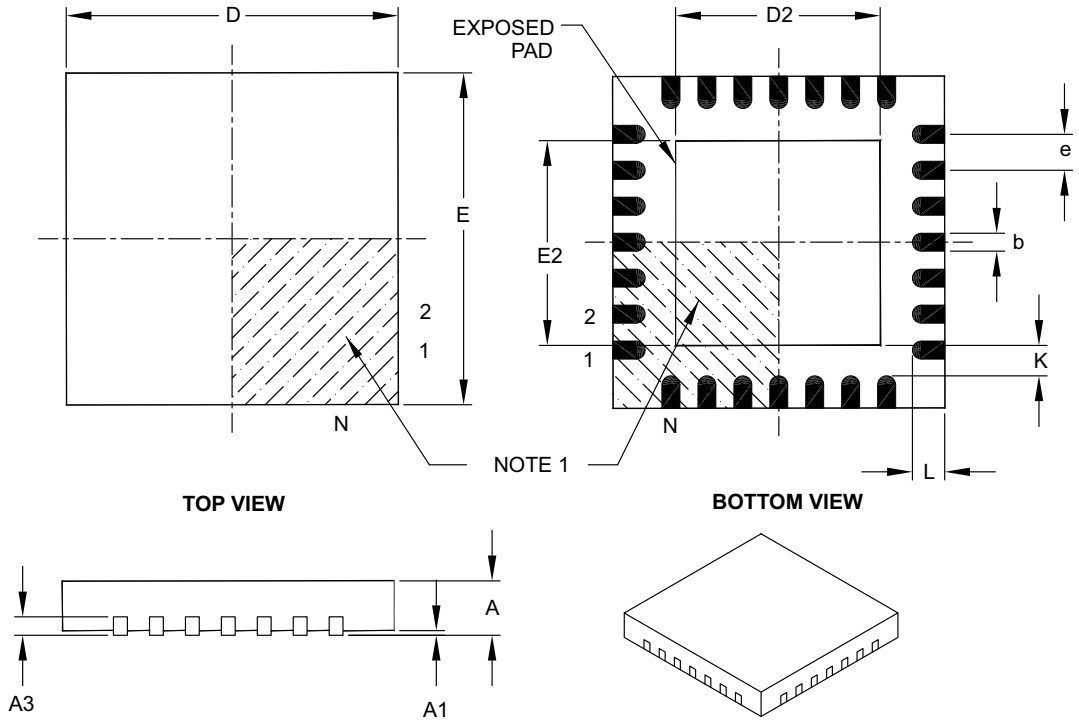


FIGURE 24-50: SCHMITT TRIGGER INPUT THRESHOLD VIN vs. VDD OVER TEMPERATURE



28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

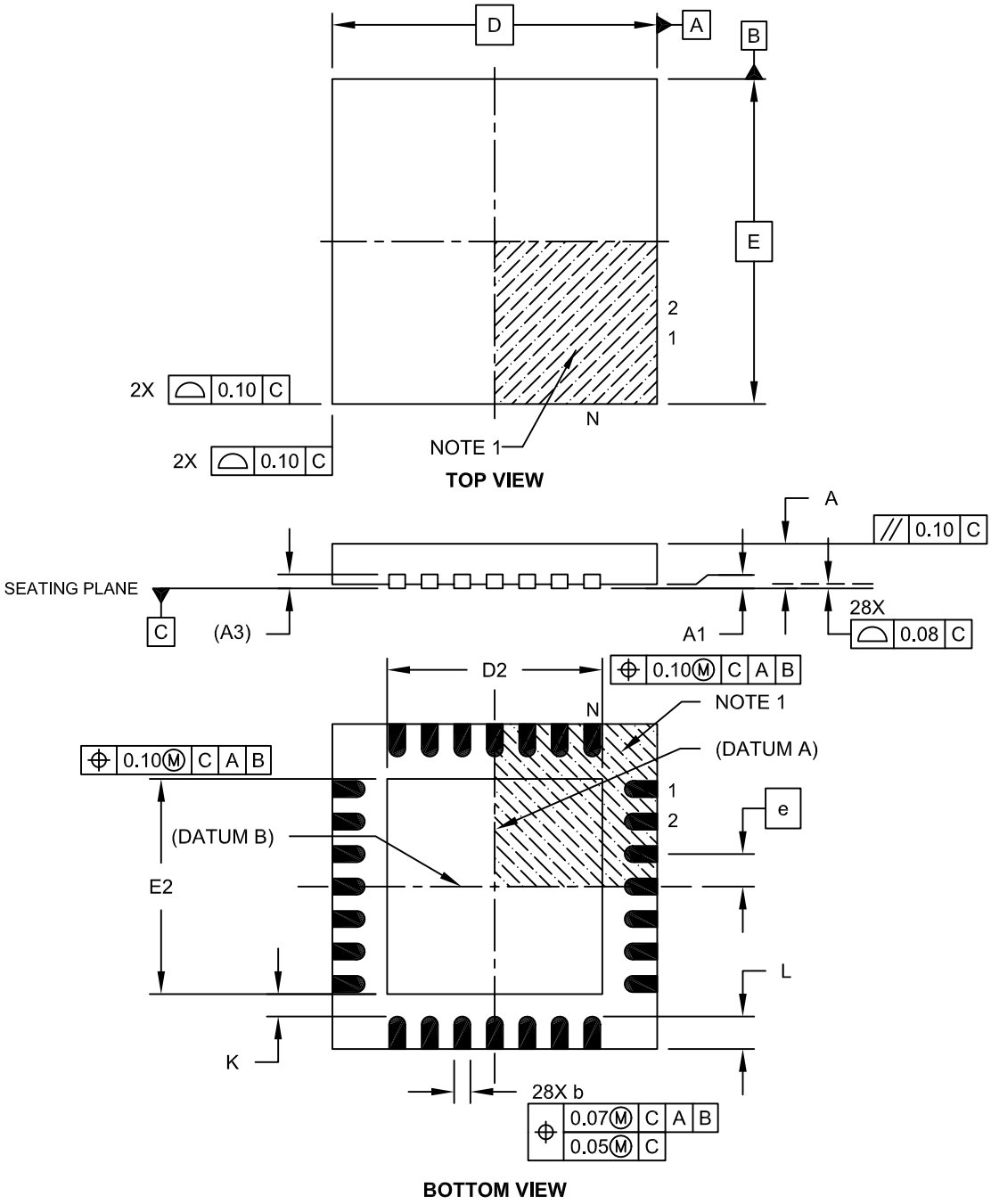
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-152A Sheet 1 of 2